



219.40446X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Vassoudevane LEBONHEUR et al.

Serial No.: 09/964,709

Filed: September 28, 2001

For: METHOD OF IMPROVING THERMAL PERFORMAMNCE IN FLIP
CHIP/INTEGRAL HEAT SPREADER PACKAGES USING LOW
MODULUS THERMAL INTERFACE MATERIAL

Attention: APPLICATION DIVISION

LETTER SUBMITTING FORMAL DRAWINGS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 12, 2003

Sir:

In response to the Notice of Allowance dated March 12, 2003, in connection with the above-identified application, attached hereto are four (4) sheets of formal drawings (Figs. 1-5, 6A-6C and 7).

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (Case No.: 219.40446X00) and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

Ronald J. Shore
Registration No. 28,577

RJS/kmh
Enclosure